Special Issue

Application of Data Science and Artificial Intelligence in Smart Manufacturing

Message from the Guest Editor

Industry 4.0 promises comprehensive support for production and product development using data science and machine learning (ML) algorithms, driven by the digitization of products and services as one of its fundamental aspects. Increased processing power and data collection would allow for the addition of intelligence into the manufacturing processes and databased decision-making approaches, enabling the realtime prediction of process performance, optimization and redefinition of products ensuring customers' needs, and reduction in costs and energy waste, all leading towards smart manufacturing (SM). I invite colleagues to contribute research dealing with recent developments and concerning the "application of data science approaches and ML techniques in smart manufacturing".

Guest Editor

Dr. Lazhar Homri

Arts et Métiers Institute of Technology, Université de Lorraine, LCFC, HESAM Université, 57070 Metz, France

Deadline for manuscript submissions

closed (31 July 2023)



Applied Sciences

an Open Access Journal by MDPI

Impact Factor 2.5 CiteScore 5.5



mdpi.com/si/136675

Applied Sciences Editorial Office MDPI, Grosspeteranlage 5 4052 Basel, Switzerland Tel: +41 61 683 77 34 applsci@mdpi.com

mdpi.com/journal/applsci





Applied Sciences

an Open Access Journal by MDPI

Impact Factor 2.5 CiteScore 5.5



About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

